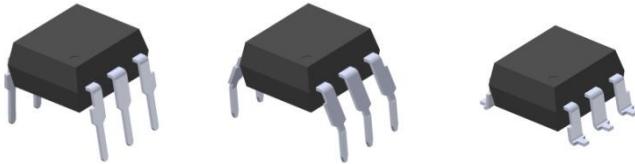


6 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLED

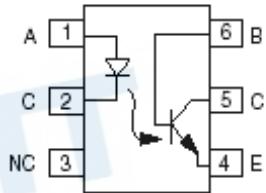
4N2X Series

4N3X Series

H11AX Series



Schematic



Pin Configuration

1. Anode
2. Cathode
3. No Connection
4. Emitter
5. Collector
6. Base

Features:

- 4N2X series: 4N25, 4N26, 4N27, 4N28
- 4N3X series: 4N35, 4N36, 4N37, 4N38
- H11AX series: H11A1, H11A2, H11A3, H11A4, H11A5
- High isolation voltage between input and output (Viso=5000 V rms)
- Creepage distance >7.62 mm
- Operating temperature up to +110°C
- Compact dual-in-line package
 - The product itself will remain within RoHS compliant version
 - Compliance with EU REACH
- UL and cUL approved(No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approval
- DEMKO approval
- FIMKO approval
- CQC approved

Description

The 4N2X, 4N3X, H11AX series of devices each consist of an infrared emitting diode optically coupled to a phototransistor.

They are packaged in a 6-pin DIP package and available in wide-lead spacing and SMD option.

Applications

- Power supply regulators
- Digital logic inputs
- Microprocessor inputs

Absolute Maximum Ratings (Ta=25°C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	I _F	60	mA
	Peak forward current (t = 10μs)	I _{FM}	1	A
	Reverse voltage	V _R	6	V
	Power dissipation (T _A = 25°C)	P _D	100	mW
	Derating factor (above 100°C)		3.8	mW/°C
Output	Collector-Emitter voltage	V _{CEO}	80	V
	Collector-Base voltage	V _{CBO}	80	V
	Emitter-Collector voltage	V _{ECO}	7	V
	Emitter-Base voltage	V _{EBO}	7	V
	Power dissipation (T _A = 25°C)	P _C	150	mW
	Derating factor (above 100°C)		9.0	mW/°C
	Total Power Dissipation	P _{TOT}	200	mW
	Isolation Voltage* ¹	V _{ISO}	5000	V rms
	Operating Temperature	T _{OPR}	-55 to 110	°C
	Storage Temperature	T _{STG}	-55 to 125	°C
	Soldering Temperature* ²	T _{SOL}	260	°C

Notes:

*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 & 3 are shorted together, and pins 4, 5 & 6 are shorted together.

*2 For 10 seconds

Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward voltage	V _F	-	1.2	1.5	V	I _F = 10mA
Reverse current	I _R	-	-	10	µA	V _R = 6V
Input capacitance	C _{in}	-	30	-	pF	V = 0, f = 1MHz

Output

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-Base dark current	I _{CBO}	-	-	20	nA	V _{CB} = 10V
Collector-Emitter dark current	I _{CEO}	-	-	50	nA	V _{CE} = 10V, IF=0mA
4N2X						
4N3X		-	-	50		V _{CE} = 60V, IF=0mA
Collector-Emitter breakdown voltage	BV _{CEO}	80	-	-	V	I _C =1mA
Collector-Base breakdown voltage	BV _{CBO}	80	-	-	V	I _C =0.1mA
Emitter-Collector breakdown voltage	BV _{ECO}	7	-	-	V	I _E =0.1mA
Emitter-Base breakdown voltage	BV _{EBO}	7	-	-	V	I _E =0.1mA
Collector-Emitter capacitance	C _{CE}	-	8	-	pF	VCE=0V, f=1MHz

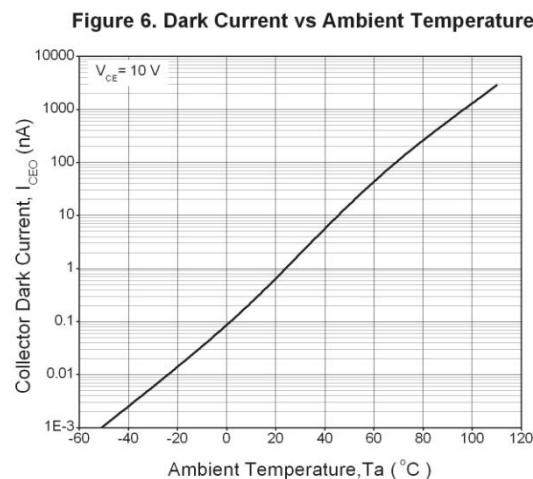
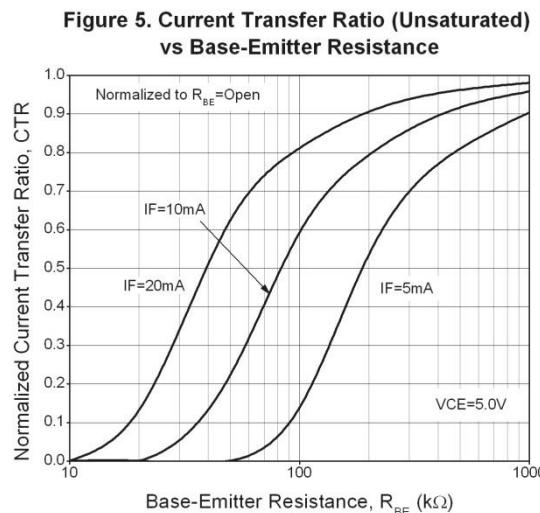
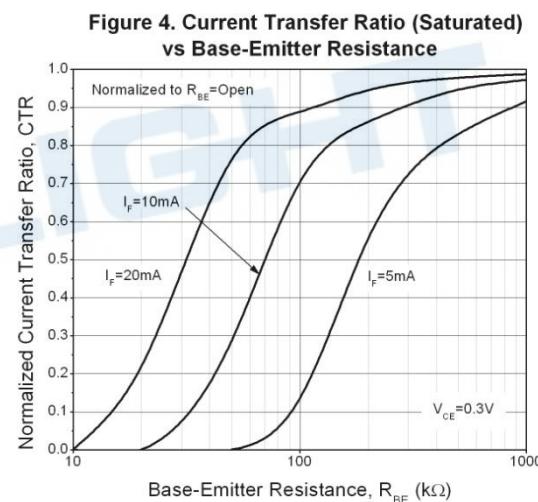
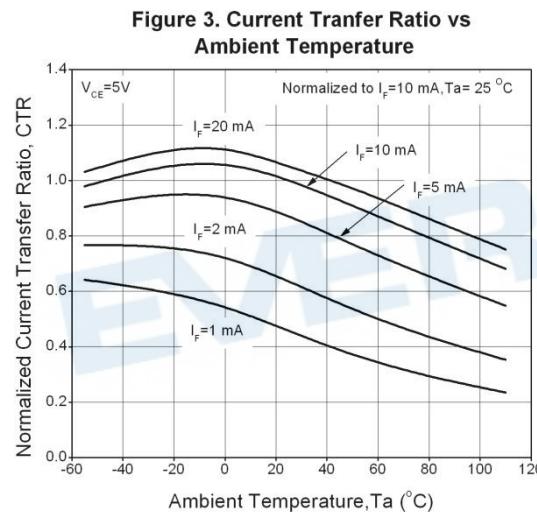
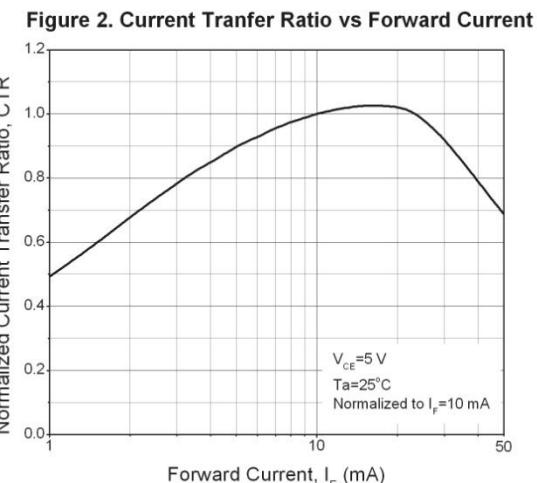
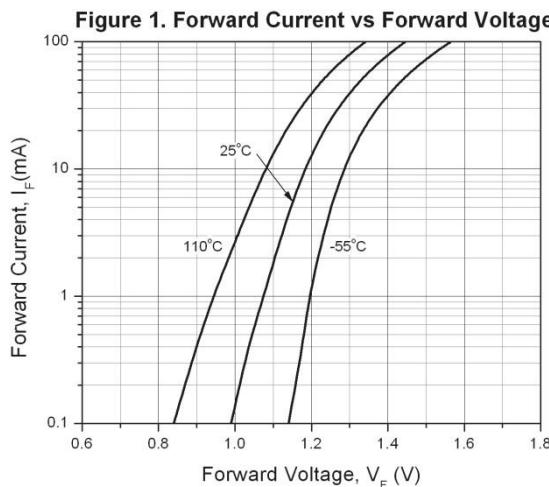
* Typical values at T_a = 25°C

Transfer Characteristics

Parameter		Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer ratio	4N35, 4N36, 4N37		100	-	-		
	H11A1		50	-	-		
	H11A5	CTR	30	-	-	%	$I_F = \pm 10\text{mA}, V_{CE} = 10\text{V}$
	4N25, 4N26, 4N38, H11A2, H11A3		20	-	-		
	4N27, 4N28, H11A4		10	-	-		
Collector-Emitter saturation voltage	4N25, 4N26, 4N27, 4N28		-	-	0.5		$I_F = 50\text{mA}, I_c = 2\text{mA}$
	4N35, 4N36, 4N37		-	-	0.3		
	H11A1, H11A2, H11A3, H11A4, H11A5	$V_{CE(sat)}$	-	-	0.4	V	$I_F = 10\text{mA}, I_c = 0.5\text{mA}$
	4N38		-	-	1.0		$I_F = 20\text{mA}, I_c = 4\text{mA}$
Isolation resistance	R_{IO}		10^{11}	-	-	Ω	$V_{IO} = 500\text{Vdc}$
Input-output capacitance	C_{IO}		-	0.2	-	pF	$V_{IO} = 0, f = 1\text{MHz}$
Turn-on time	4N25, 4N26, 4N27, 4N28, H11A1, H11A2, H11A3, H11A4, H11A5	T_{on}	-	3	10	μs	$V_{CC} = 10\text{V}, I_F = 10\text{mA}, R_L = 100\Omega$ See Fig. 11
	4N35, 4N36, 4N37, 4N38		-	10	12		$V_{CC} = 10\text{V}, I_c = 2\text{mA}, R_L = 100\Omega$, See Fig. 11
Turn-off time	4N25, 4N26, 4N27, 4N28, H11A1, H11A2, H11A3, H11A4, H11A5	T_{off}	-	3	10	μs	$V_{CC} = 10\text{V}, I_F = 10\text{mA}, R_L = 100\Omega$ See Fig. 11
	4N35, 4N36, 4N37, 4N38		-	9	12		$V_{CC} = 10\text{V}, I_c = 2\text{mA}, R_L = 100\Omega$, See Fig. 11

* Typical values at $T_a = 25^\circ\text{C}$

Typical Electro-Optical Characteristics Curves



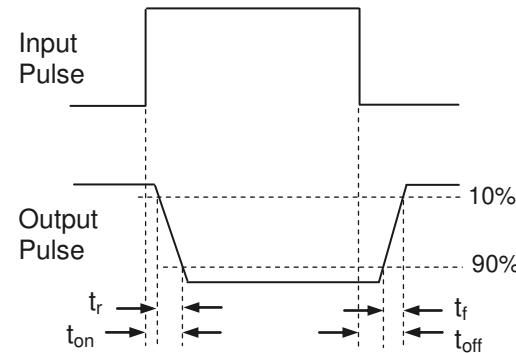
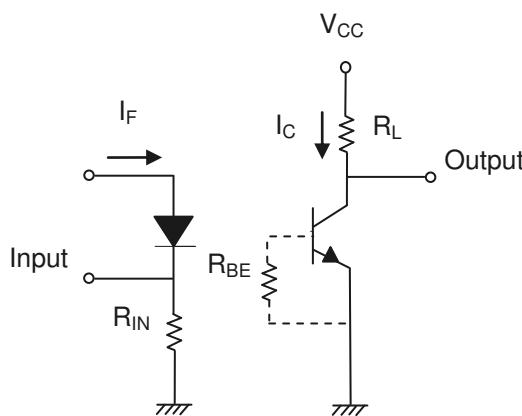
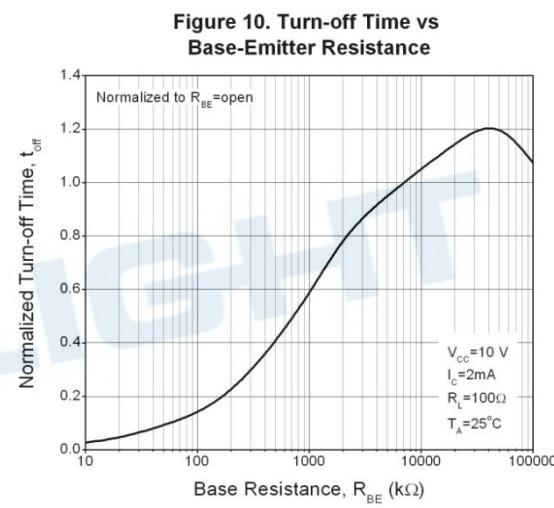
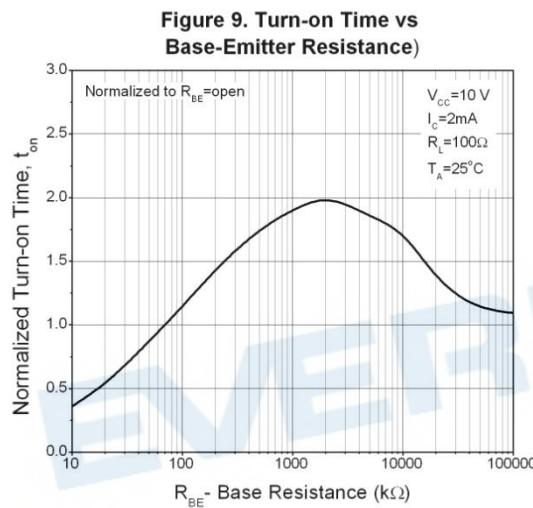
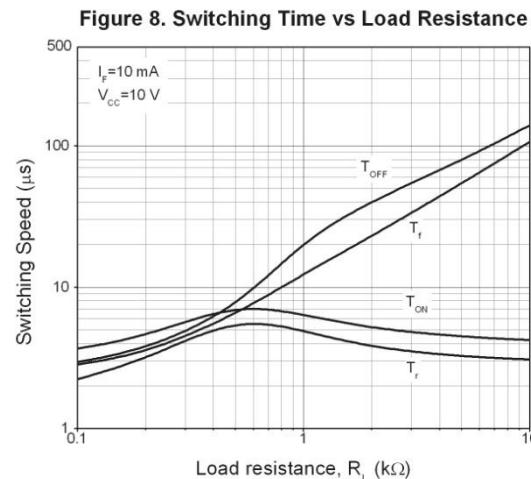
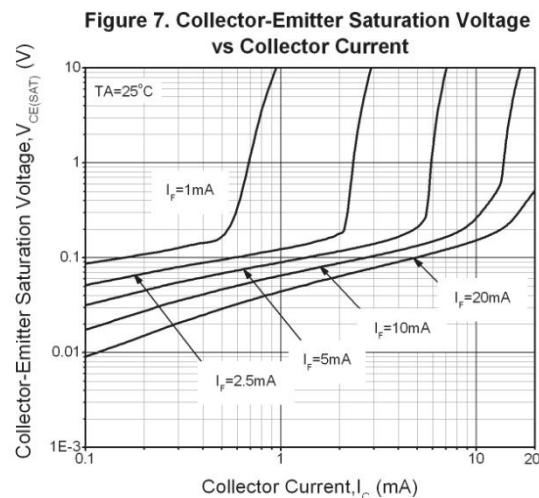


Figure 11. Switching Time Test Circuit & Waveforms

Order Information

Part Number

4NXXY(Z)-V

or

H11AXY(Z)-V

Note

XX = Part no. for 4NXX series (25, 26, 27, 28, 35, 36, 37 or 38)

X = Part no. for H11AX series (1, 2, 3, 4, or 5)

Y = Lead form option (S, S1, M or none)

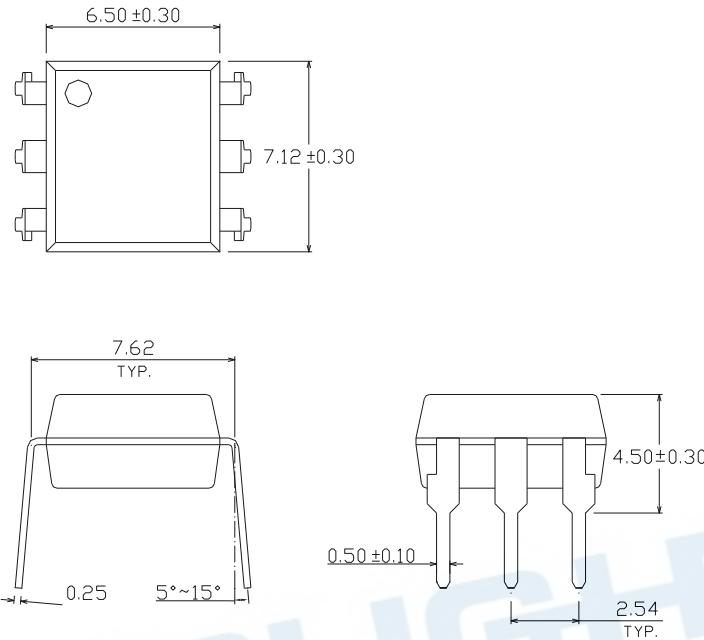
Z = Tape and reel option (TA, TB or none).

V = VDE safety (optional)

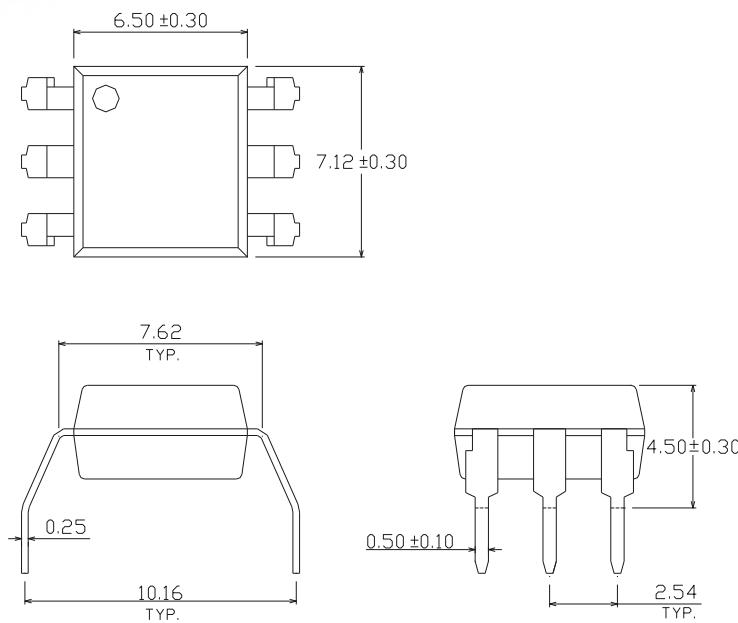
Option	Description	Packing quantity
None	Standard DIP-6	65 units per tube
M	Wide lead bend (0.4 inch spacing)	65 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel

Package Dimension (Dimensions in mm)

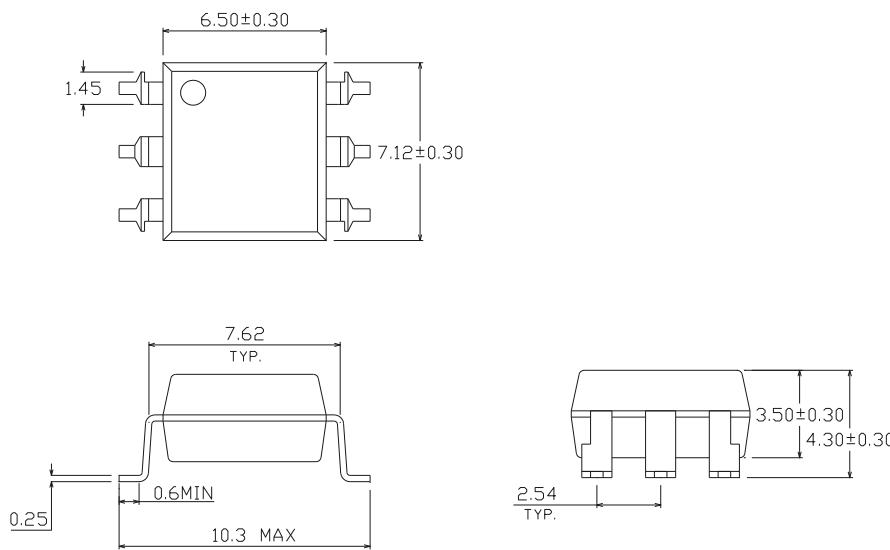
Standard DIP Type



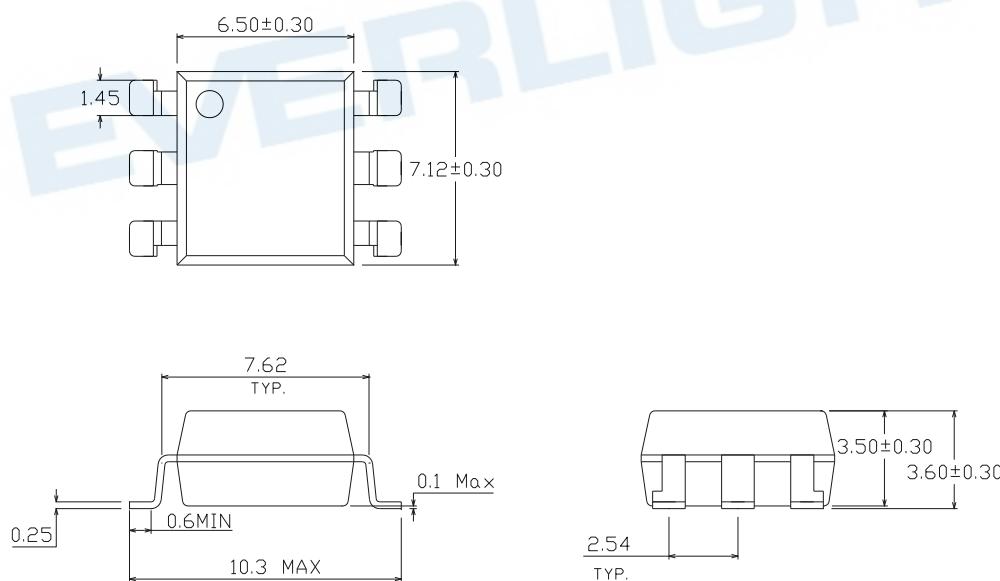
Option M Type



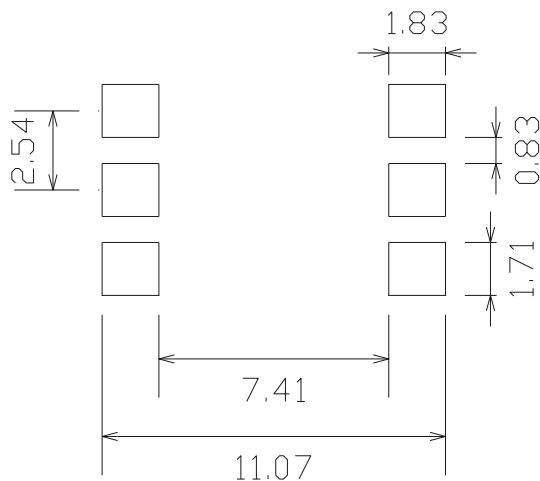
Option S Type



Option S1 Type



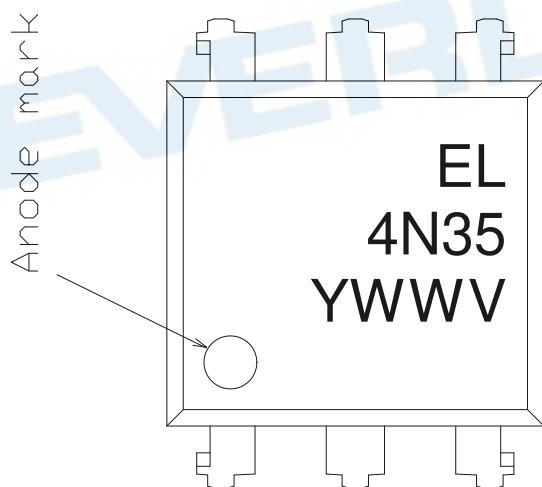
Recommended pad layout for surface mount leadform



Notes

Suggested pad dimension is just for reference only.
Please modify the pad dimension based on individual need.

Device Marking

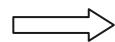
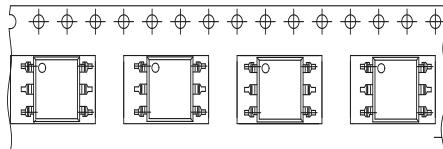


Notes

EL	denotes Everlight
4N35	denotes Device Number
Y	denotes 1 digit Year code
WW	denotes 2 digit Week code
V	denotes VDE (optional)

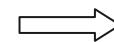
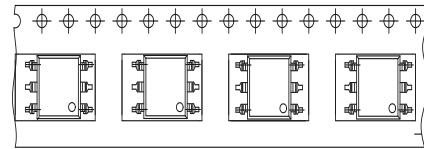
Tape & Reel Packing Specifications

Option TA



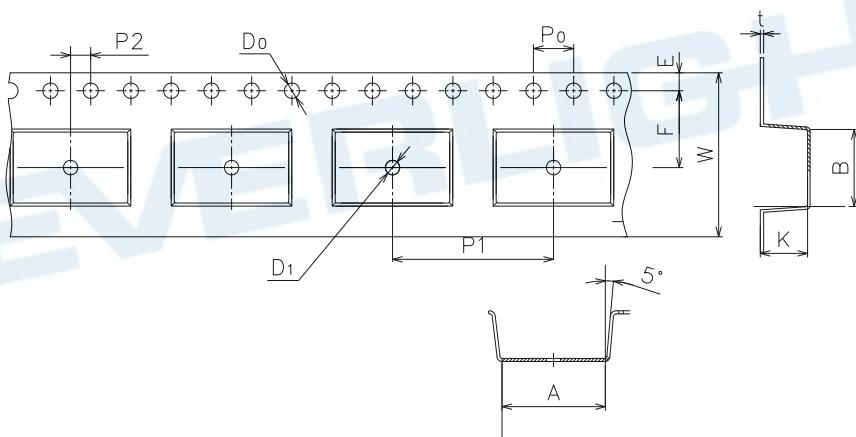
Direction of feed from reel

Option TB



Direction of feed from reel

Tape dimensions

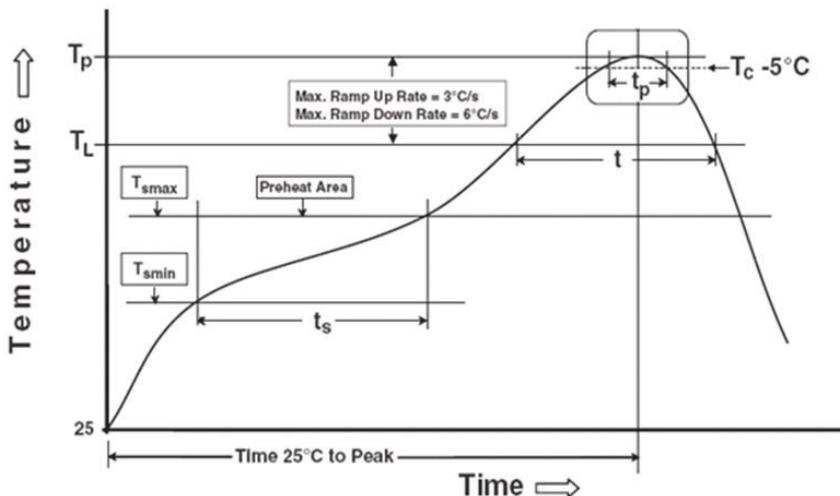


Dimension No.	A	B	Do	D1	E	F
Dimension (mm)	10.8 ± 0.1	7.55 ± 0.1	1.5 ± 0.1	$1.5 + 0.1 / -0$	1.75 ± 0.1	7.5 ± 0.1
Dimension No.	Po	P1	P2	t	W	K
Dimension (mm)	4.0 ± 0.15	12 ± 0.1	2.0 ± 0.1	0.35 ± 0.03	16.0 ± 0.2	4.5 ± 0.1

Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200°C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_p)	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

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